

SN54LV157A, SN74LV157A QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS

SCLS397F – APRIL 1998 – REVISED APRIL 2005

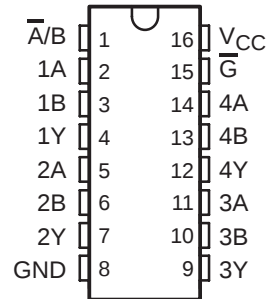
- 2-V to 5.5-V V_{CC} Operation
- Max t_{pd} of 7.5 ns at 5 V
- Typical V_{OLP} (Output Ground Bounce)
<0.8 V at V_{CC} , $T_A = 25^\circ\text{C}$
- Typical V_{OHV} (Output V_{OH} Undershoot)
>2.3 V at V_{CC} , $T_A = 25^\circ\text{C}$
- I_{off} Supports Partial-Power-Down-Mode Operation
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

description/ordering information

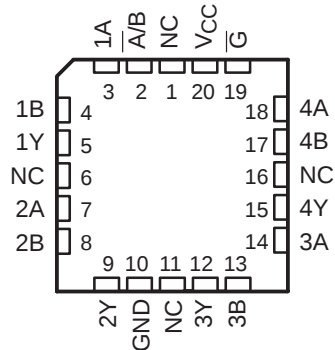
The 'LV157A devices are quadruple 2-line to 1-line data selectors/multiplexers designed for 2-V to 5.5-V V_{CC} operation.

These devices contain inverters and drivers to supply full data selection to the four output gates. A separate strobe ($\bar{G}$) input is provided. A 4-bit word is selected from one of two sources and is routed to the four outputs. The 'LV157A devices present true data.

SN54LV157A . . . J OR W PACKAGE
SN74LV157A . . . D, DB, DGV, NS, OR PW PACKAGE
(TOP VIEW)



SN54LV157A . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

ORDERING INFORMATION

T_A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	SOIC – D	Tube of 40	SN74LV157AD	LV157A
		Reel of 2500	SN74LV157ADR	
	SOP – NS	Reel of 2000	SN74LV157ANSR	74LV157A
	SSOP – DB	Reel of 2000	SN74LV157ADBR	LV157A
	TSSOP – PW	Tube of 90	SN74LV157APW	LV157A
		Reel of 2000	SN74LV157APWR	
		Reel of 250	SN74LV157APWT	
–55°C to 125°C	TVSOP – DGV	Reel of 2000	SN74LV157ADGVR	LV157A
	CDIP – J	Tube of 25	SNJ54LV157AJ	SNJ54LV157AJ
	CFP – W	Tube of 150	SNJ54LV157AW	SNJ54LV157AW
	LCCC – FK	Tube of 55	SNJ54LV157AFK	SNJ54LV157AFK

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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**TEXAS
INSTRUMENTS**

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SN54LV157A, SN74LV157A

QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS

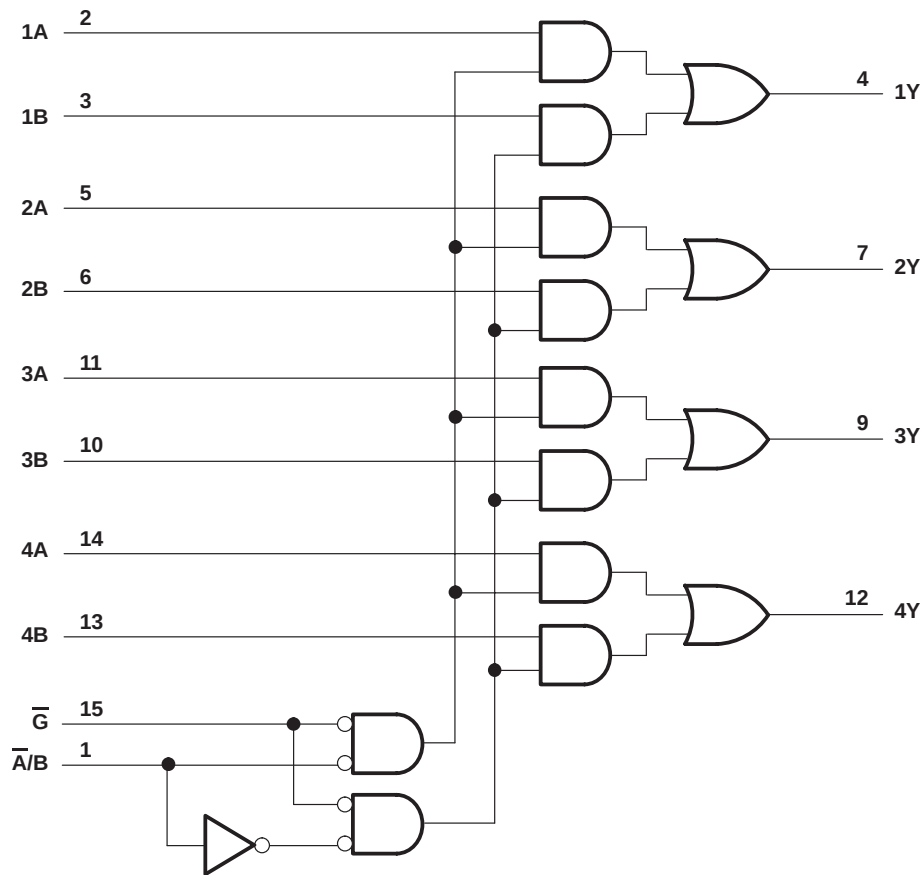
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description/ordering information (continued)

These devices are fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down.

FUNCTION TABLE				
INPUTS				OUTPUT Y
$\overline{G}$	SELECT $\overline{A/B}$	DATA		
		A	B	
H	X	X	X	L
L	L	L	X	L
L	L	H	X	H
L	H	X	L	L
L	H	X	H	H

logic diagram (positive logic)



Pin numbers shown are for the D, DB, DGV, J, NS, PW, and W packages.

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QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Output voltage range applied in high or low state, V_O (see Notes 1 and 2)	–0.5 V to $V_{CC} + 0.5$ V
Output voltage range applied in power-off state, V_O (see Note 1)	–0.5 V to 7 V
Input clamp current, I_{IK} ($V_I < 0$)	–20 mA
Output clamp current, I_{OK} ($V_O < 0$)	–50 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±25 mA
Continuous current through V_{CC} or GND	±50 mA
Package thermal impedance, θ_{JA} (see Note 3): D package	73°C/W
DB package	82°C/W
DGV package	120°C/W
NS package	64°C/W
PW package	108°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES:
1. The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
 2. This value is limited to 5.5 V maximum.
 3. The package thermal impedance is calculated in accordance with JESD 51-7.



SN54LV157A, SN74LV157A

QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS

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recommended operating conditions (see Note 4)

			SN54LV157A		SN74LV157A		UNIT
			MIN	MAX	MIN	MAX	
V _{CC}	Supply voltage		2	5.5	2	5.5	V
V _{IH}	High-level input voltage	V _{CC} = 2 V	1.5		1.5		V
		V _{CC} = 2.3 V to 2.7 V	V _{CC} × 0.7		V _{CC} × 0.7		
		V _{CC} = 3 V to 3.6 V	V _{CC} × 0.7		V _{CC} × 0.7		
		V _{CC} = 4.5 V to 5.5 V	V _{CC} × 0.7		V _{CC} × 0.7		
V _{IL}	Low-level input voltage	V _{CC} = 2 V	0.5		0.5		V
		V _{CC} = 2.3 V to 2.7 V	V _{CC} × 0.3		V _{CC} × 0.3		
		V _{CC} = 3 V to 3.6 V	V _{CC} × 0.3		V _{CC} × 0.3		
		V _{CC} = 4.5 V to 5.5 V	V _{CC} × 0.3		V _{CC} × 0.3		
V _I	Input voltage		0	5.5	0	5.5	V
V _O	Output voltage		0	V _{CC}	0	V _{CC}	V
I _{OH}	High-level output current	V _{CC} = 2 V	−50		−50		μA
		V _{CC} = 2.3 V to 2.7 V	−2		−2		mA
		V _{CC} = 3 V to 3.6 V	−6		−6		
		V _{CC} = 4.5 V to 5.5 V	−12		−12		
I _{OL}	Low-level output current	V _{CC} = 2 V	50		50		μA
		V _{CC} = 2.3 V to 2.7 V	2		2		mA
		V _{CC} = 3 V to 3.6 V	6		6		
		V _{CC} = 4.5 V to 5.5 V	12		12		
Δt/Δv	Input transition rise or fall rate	V _{CC} = 2.3 V to 2.7 V	200		0	200	ns/V
		V _{CC} = 3 V to 3.6 V	100		0	100	
		V _{CC} = 4.5 V to 5.5 V	20		0	20	
T _A	Operating free-air temperature		−55	125	−40	85	°C

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	SN54LV157A			SN74LV157A			UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	
V _{OH}	I _{OH} = -50 μA	2 V to 5.5 V	V _{CC} -0.1			V _{CC} -0.1			V
	I _{OH} = -2 mA	2.3 V	2			2			
	I _{OH} = -6 mA	3 V	2.48			2.48			
	I _{OH} = -12 mA	4.5 V	3.8			3.8			
V _{OL}	I _{OL} = 50 μA	2 V to 5.5 V	0.1			0.1			V
	I _{OL} = 2 mA	2.3 V	0.4			0.4			
	I _{OL} = 6 mA	3 V	0.44			0.44			
	I _{OL} = 12 mA	4.5 V	0.55			0.55			
I _I	V _I = 5.5 V or GND	0 to 5.5 V	±1			±1			μA
I _{CC}	V _I = V _{CC} or GND, I _O = 0	5.5 V	20			20			μA
I _{off}	V _I or V _O = 0 to 5.5 V	0	5			5			μA
C _i	V _I = V _{CC} or GND	3.3 V	1.7			1.7			pF

PRODUCT PREVIEW information concerns products in the formative or design phase of development. Characteristic data and other specifications are design goals. Texas Instruments reserves the right to change or discontinue these products without notice.



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QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS

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**switching characteristics over recommended operating free-air temperature range,
V_{CC} = 2.5 V ± 0.2 V (unless otherwise noted) (see Figure 1)**

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	T _A = 25°C			SN54LV157A		SN74LV157A		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t _{pd}	A or B	Y	C _L = 15 pF	7.4*	15.9*	1*	19.5*	1	19.5		ns
	$\overline{A/B}$	Y		7.9*	19.4*	1*	23.5*	1	23.5		
	$\overline{G}$	Y		7.8*	19.8*	1*	24*	1	24		
t _{pd}	A or B	Y	C _L = 50 pF	9.4	18.8	1	22	1	22		ns
	$\overline{A/B}$	Y		10.8	22.3	1	26	1	26		
	$\overline{G}$	Y		9.6	22.7	1	26.5	1	26.5		

* On products compliant to MIL-PRF-38535, this parameter is not production tested.

**switching characteristics over recommended operating free-air temperature range,
V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)**

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	T _A = 25°C			SN54LV157A		SN74LV157A		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t _{pd}	A or B	Y	C _L = 15 pF	5.2*	9.7*	1*	11.5*	1	11.5		ns
	$\overline{A/B}$	Y		5.8*	13.2*	1*	15.5*	1	15.5		
	$\overline{G}$	Y		5.5*	13.6*	1*	16*	1	16		
t _{pd}	A or B	Y	C _L = 50 pF	6.7	13.2	1	15	1	15		ns
	$\overline{A/B}$	Y		7.6	16.7	1	19	1	19		
	$\overline{G}$	Y		7	17.1	1	19.5	1	19.5		

* On products compliant to MIL-PRF-38535, this parameter is not production tested.

**switching characteristics over recommended operating free-air temperature range,
V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)**

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	T _A = 25°C			SN54LV157A		SN74LV157A		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t _{pd}	A or B	Y	C _L = 15 pF	3.6*	6.4*	1*	7.5*	1	7.5		ns
	$\overline{A/B}$	Y		4.1*	8.1*	1*	9.5*	1	9.5		
	$\overline{G}$	Y		3.8*	8.6*	1*	10*	1	10		
t _{pd}	A or B	Y	C _L = 50 pF	4.8	8.4	1	9.5	1	9.5		ns
	$\overline{A/B}$	Y		5.4	10.1	1	11.5	1	11.5		
	$\overline{G}$	Y		5	10.6	1	12	1	12		

* On products compliant to MIL-PRF-38535, this parameter is not production tested.

noise characteristics, V_{CC} = 3.3 V, C_L = 50 pF, T_A = 25°C (see Note 5)

PARAMETER		SN74LV157A			UNIT
		MIN	TYP	MAX	
V _{OL(P)}	Quiet output, maximum dynamic V _{OL}		0.3	0.8	V
V _{OL(V)}	Quiet output, minimum dynamic V _{OL}		–0.1	–0.8	V
V _{OH(V)}	Quiet output, minimum dynamic V _{OH}		3.2		V
V _{IH(D)}	High-level dynamic input voltage		2.31		V
V _{IL(D)}	Low-level dynamic input voltage			0.99	V

NOTE 5: Characteristics are for surface-mount packages only.

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operating characteristics, $T_A = 25^\circ\text{C}$

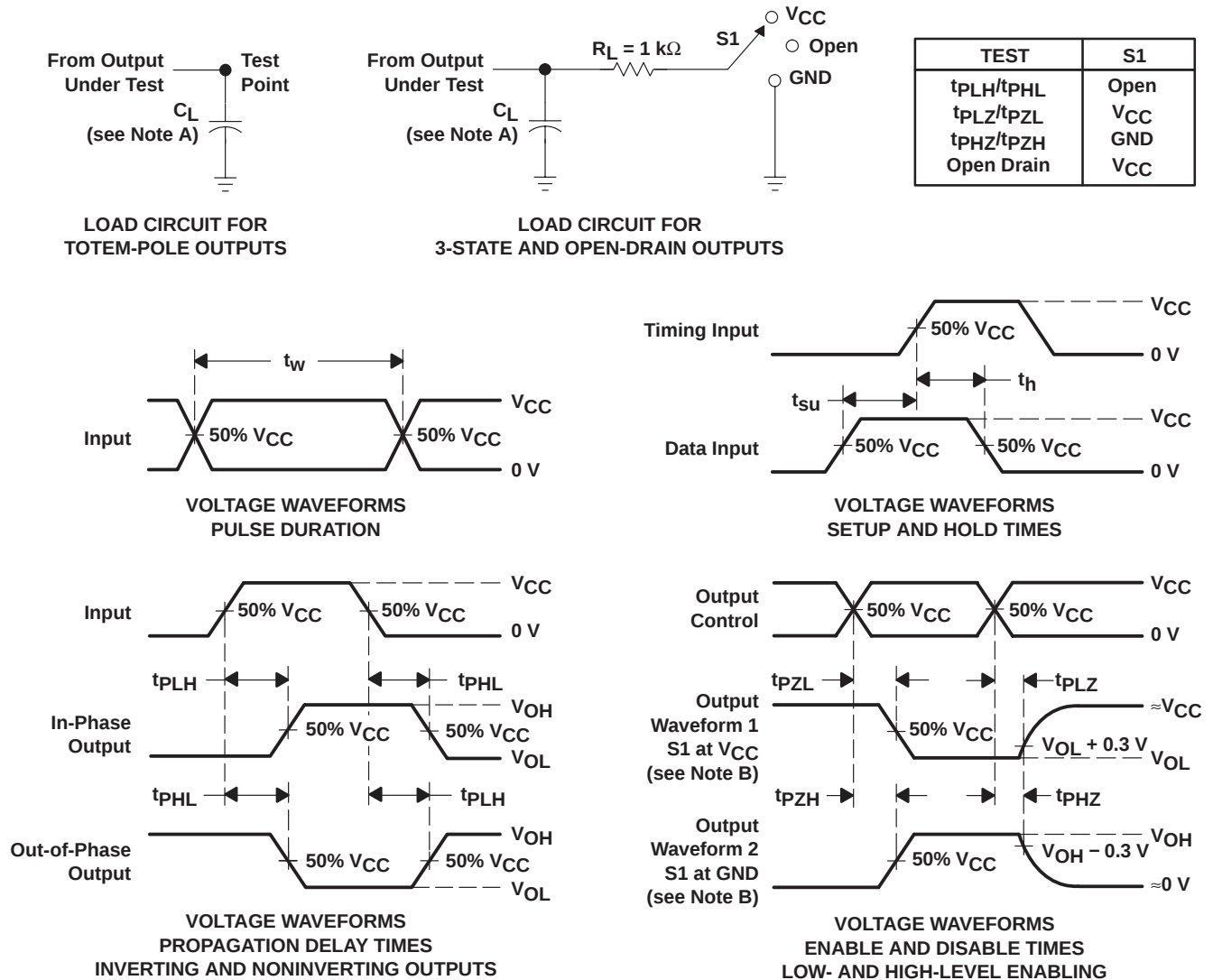
PARAMETER	TEST CONDITIONS	V _{CC}	TYP	UNIT
C _{pd} Power dissipation capacitance	C _L = 50 pF, f = 10 MHz	3.3 V	12.1	pF
		5 V	13.1	



SN54LV157A, SN74LV157A QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS

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PARAMETER MEASUREMENT INFORMATION



- NOTES:
- C_L includes probe and jig capacitance.
 - Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - All input pulses are supplied by generators having the following characteristics: $PRR \leq 1\text{ MHz}$, $Z_O = 50\ \Omega$, $t_r \leq 3\text{ ns}$, $t_f \leq 3\text{ ns}$.
 - The outputs are measured one at a time, with one input transition per measurement.
 - t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - t_{PZL} and t_{PZH} are the same as t_{en} .
 - t_{PHL} and t_{PLH} are the same as t_{pd} .
 - All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LV157AD	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV157A	Samples
SN74LV157ADBR	ACTIVE	SSOP	DB	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV157A	Samples
SN74LV157ADGVR	ACTIVE	TVSOP	DGV	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV157A	Samples
SN74LV157ADR	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV157A	Samples
SN74LV157ADRG4	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV157A	Samples
SN74LV157ANSR	ACTIVE	SO	NS	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	74LV157A	Samples
SN74LV157APW	ACTIVE	TSSOP	PW	16	90	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV157A	Samples
SN74LV157APWG4	ACTIVE	TSSOP	PW	16	90	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV157A	Samples
SN74LV157APWR	ACTIVE	TSSOP	PW	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV157A	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

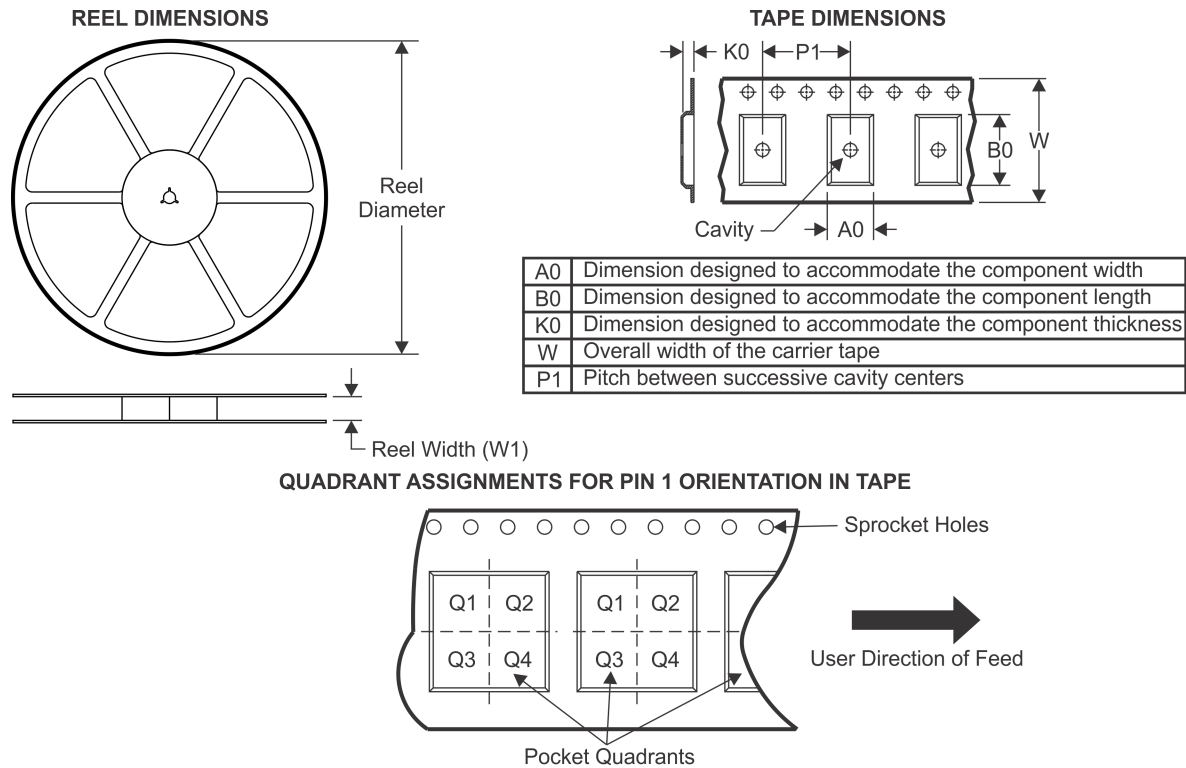
⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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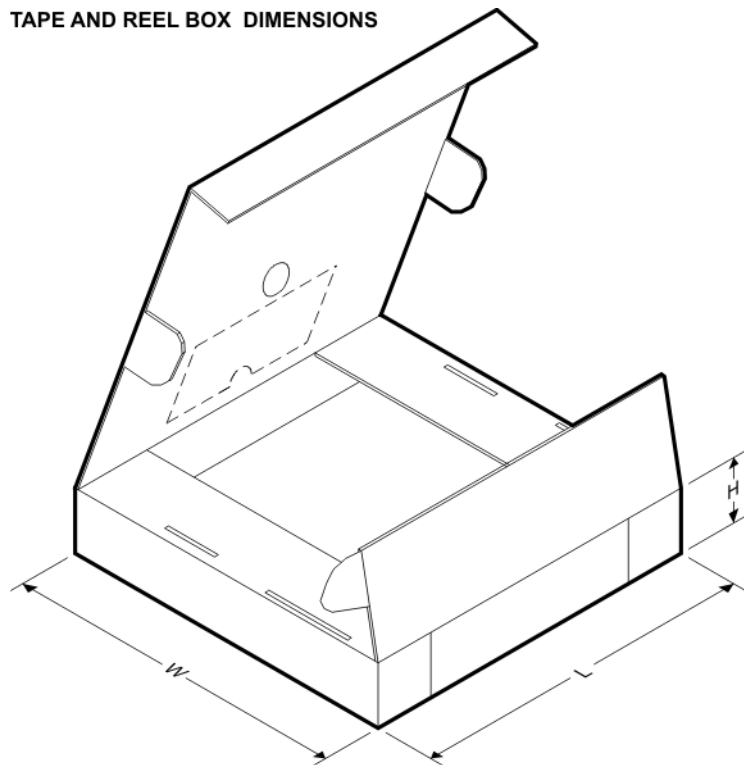
TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LV157ADBR	SSOP	DB	16	2000	330.0	16.4	8.35	6.6	2.4	12.0	16.0	Q1
SN74LV157ADGVR	TVSOP	DGV	16	2000	330.0	12.4	6.8	4.0	1.6	8.0	12.0	Q1
SN74LV157ADR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74LV157ANSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74LV157APWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

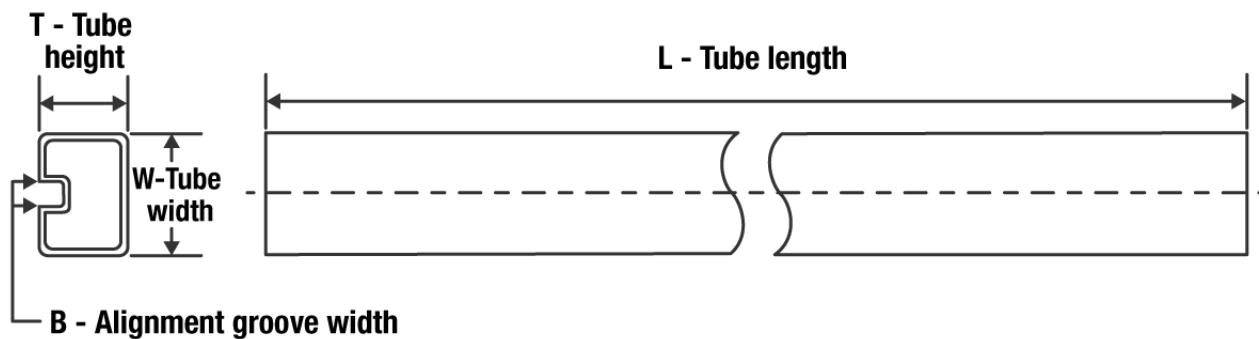
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

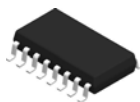
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LV157ADBR	SSOP	DB	16	2000	853.0	449.0	35.0
SN74LV157ADGVR	TVSOP	DGV	16	2000	853.0	449.0	35.0
SN74LV157ADR	SOIC	D	16	2500	340.5	336.1	32.0
SN74LV157ANSR	SO	NS	16	2000	853.0	449.0	35.0
SN74LV157APWR	TSSOP	PW	16	2000	853.0	449.0	35.0

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
SN74LV157AD	D	SOIC	16	40	507	8	3940	4.32
SN74LV157APW	PW	TSSOP	16	90	530	10.2	3600	3.5
SN74LV157APWG4	PW	TSSOP	16	90	530	10.2	3600	3.5

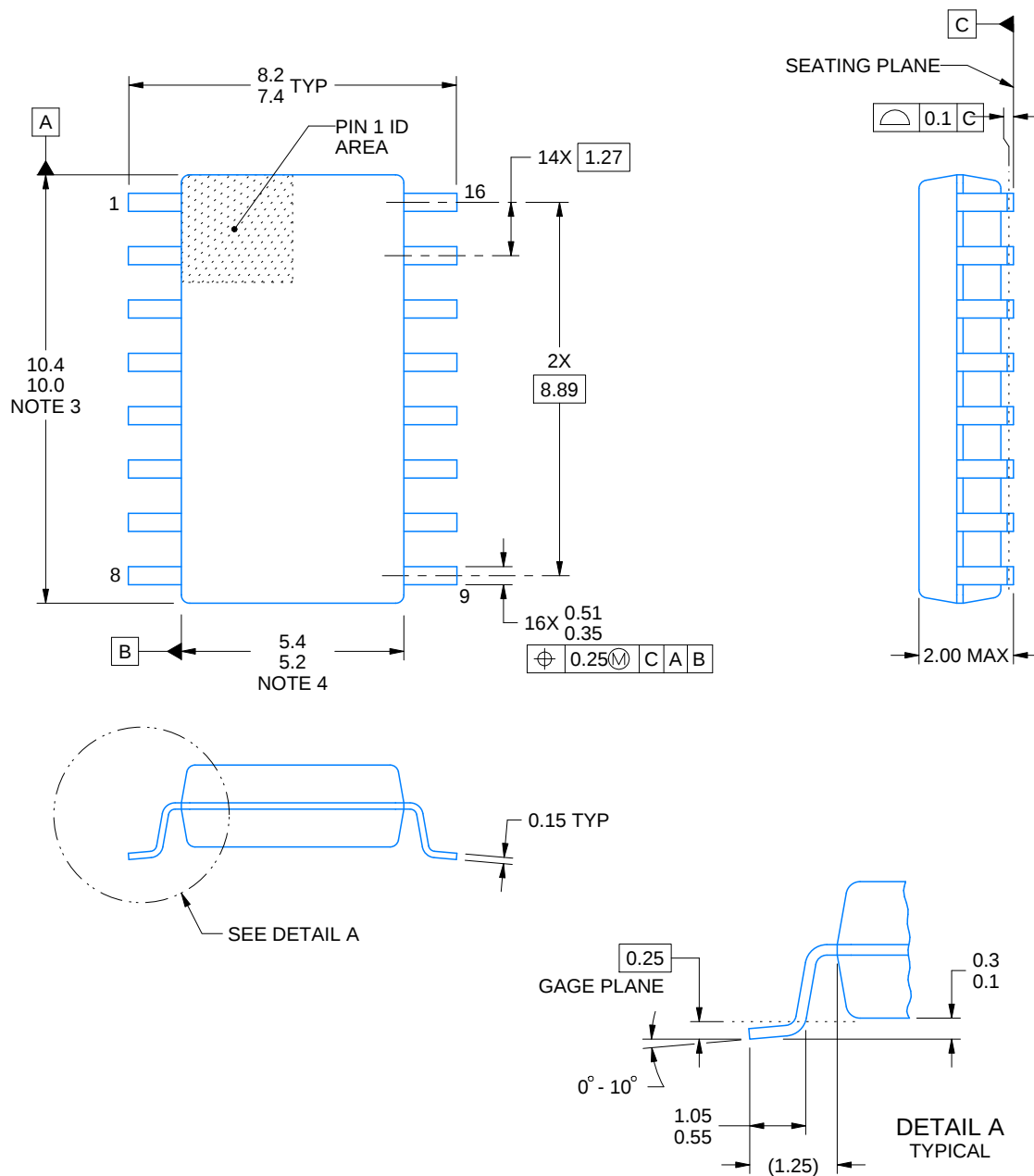


PACKAGE OUTLINE

NS0016A

SOP - 2.00 mm max height

SOP



4220735/A 12/2021

NOTES:

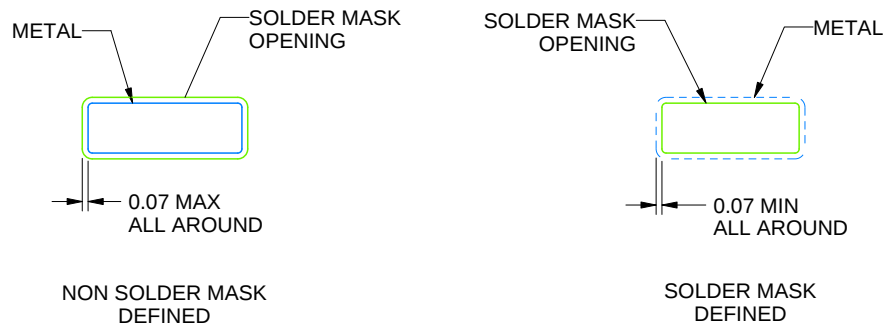
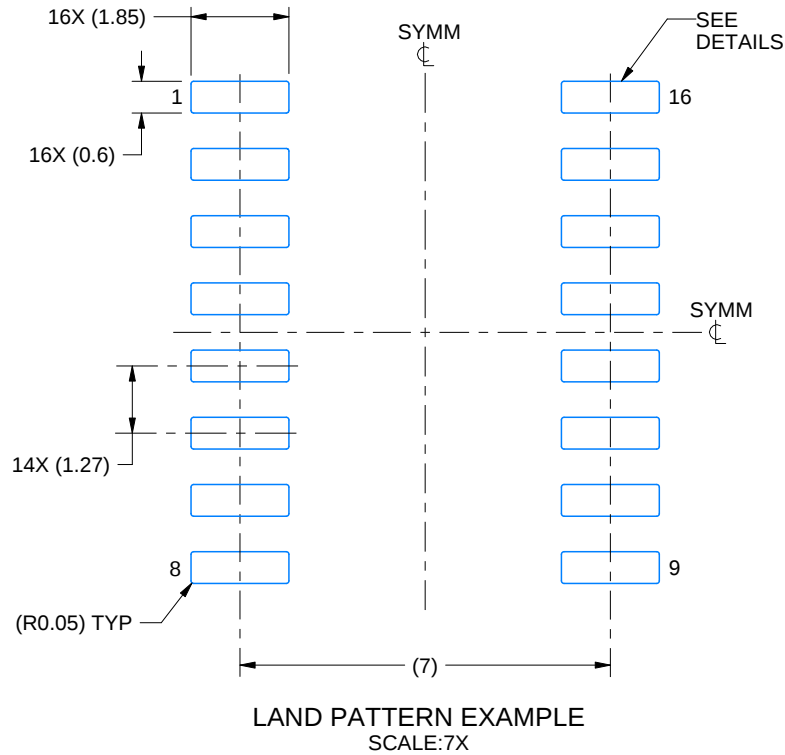
1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.

EXAMPLE BOARD LAYOUT

NS0016A

SOP - 2.00 mm max height

SOP



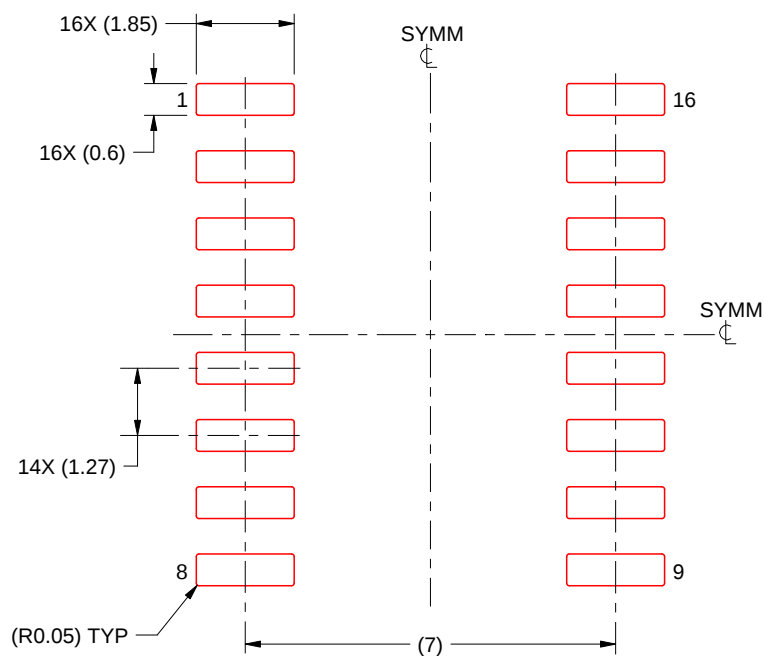
SOLDER MASK DETAILS

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NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.

6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
 BASED ON 0.125 mm THICK STENCIL
 SCALE:7X

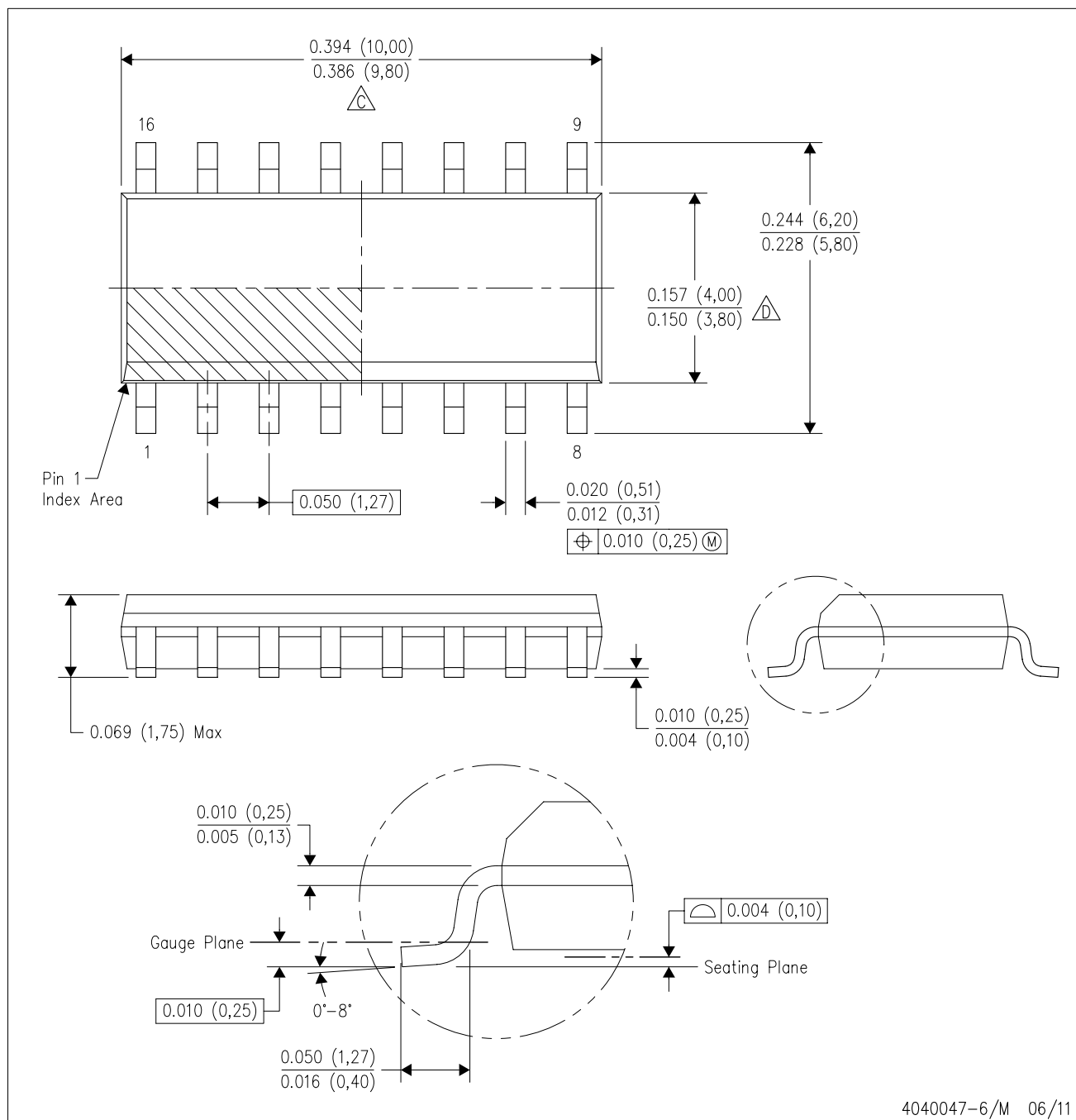
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NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

D (R-PDSO-G16)

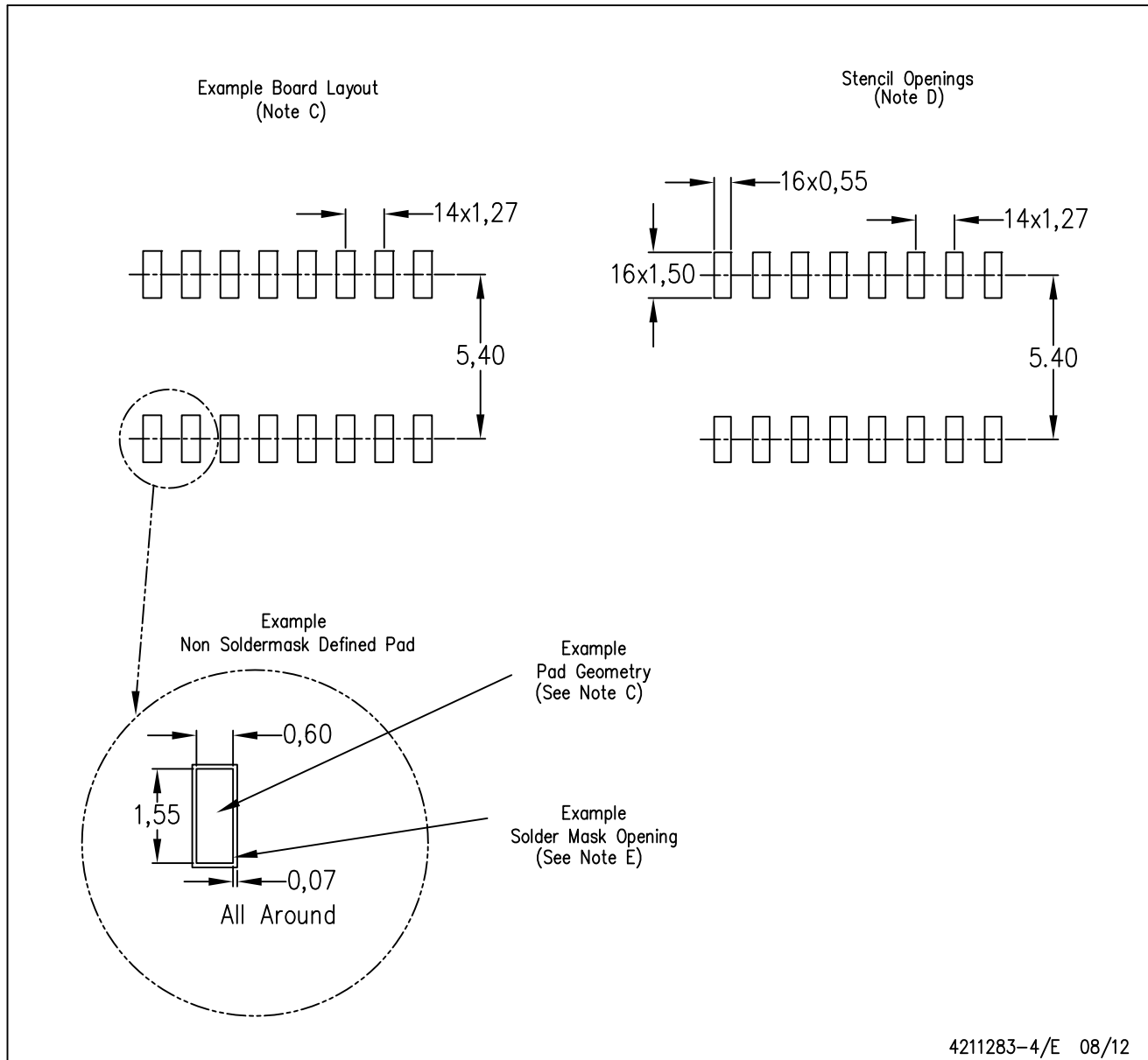
PLASTIC SMALL OUTLINE



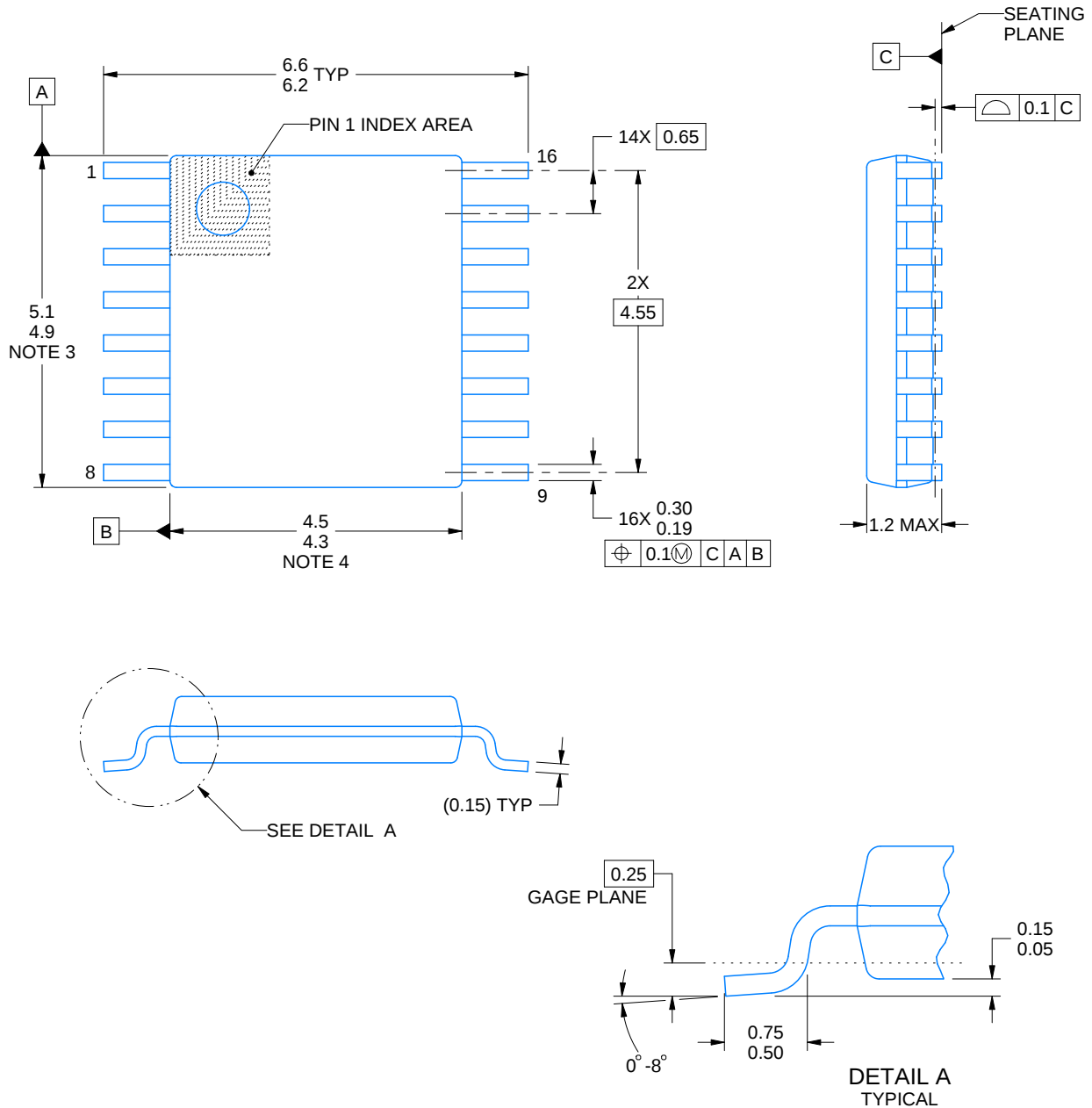
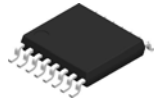
NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 E. Reference JEDEC MS-012 variation AC.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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NOTES:

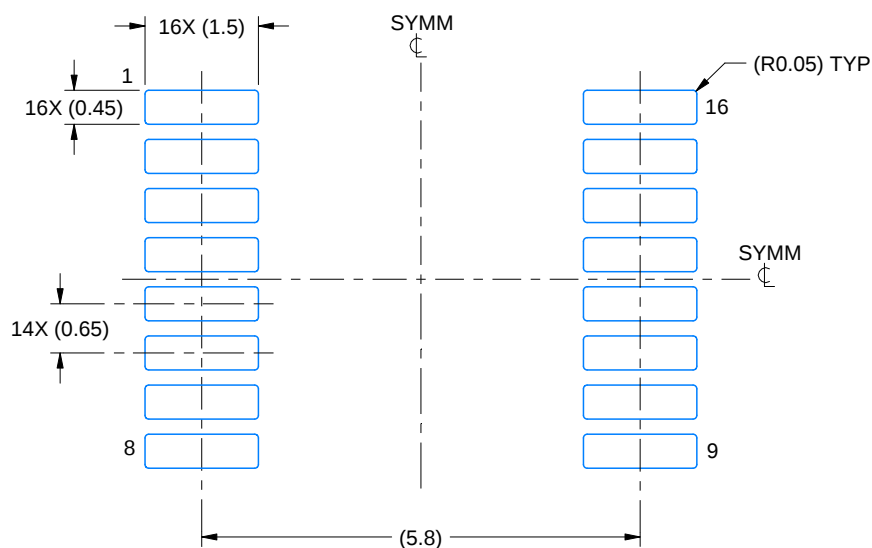
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

EXAMPLE BOARD LAYOUT

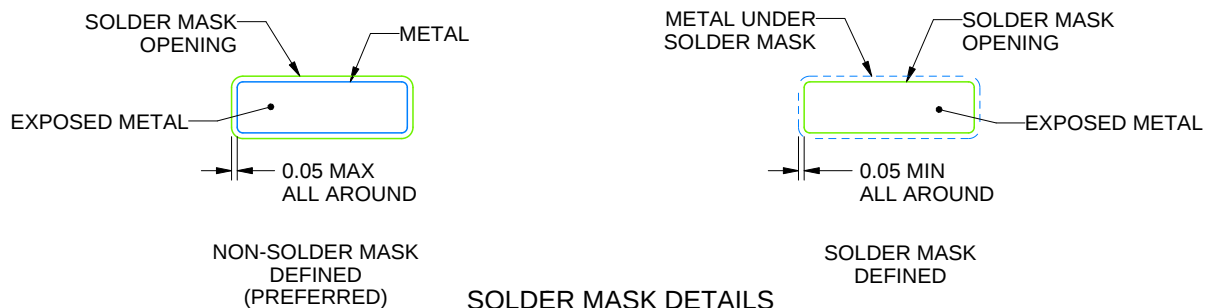
PW0016A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



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NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

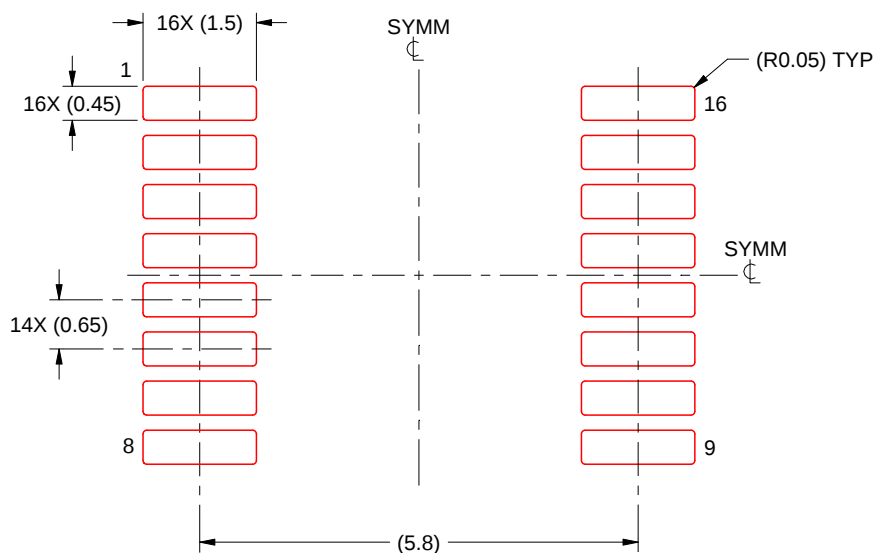
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

PW0016A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

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NOTES: (continued)

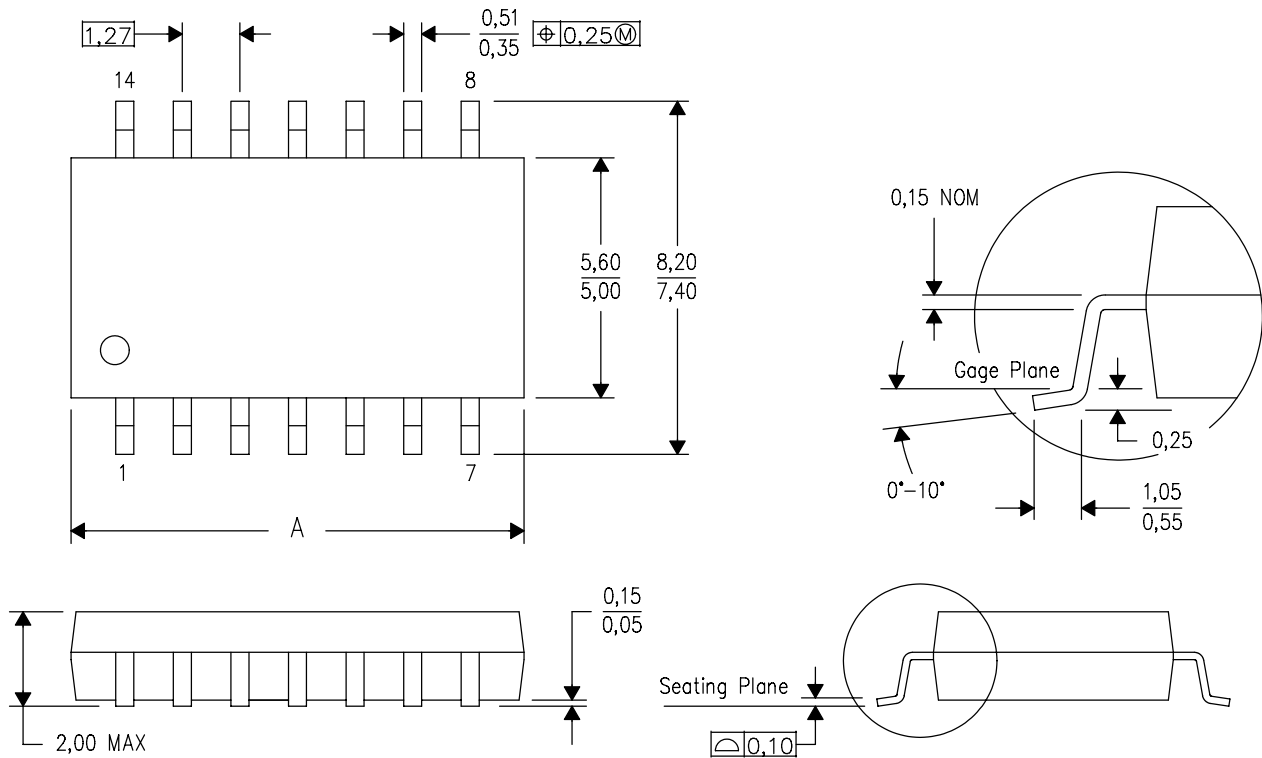
8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

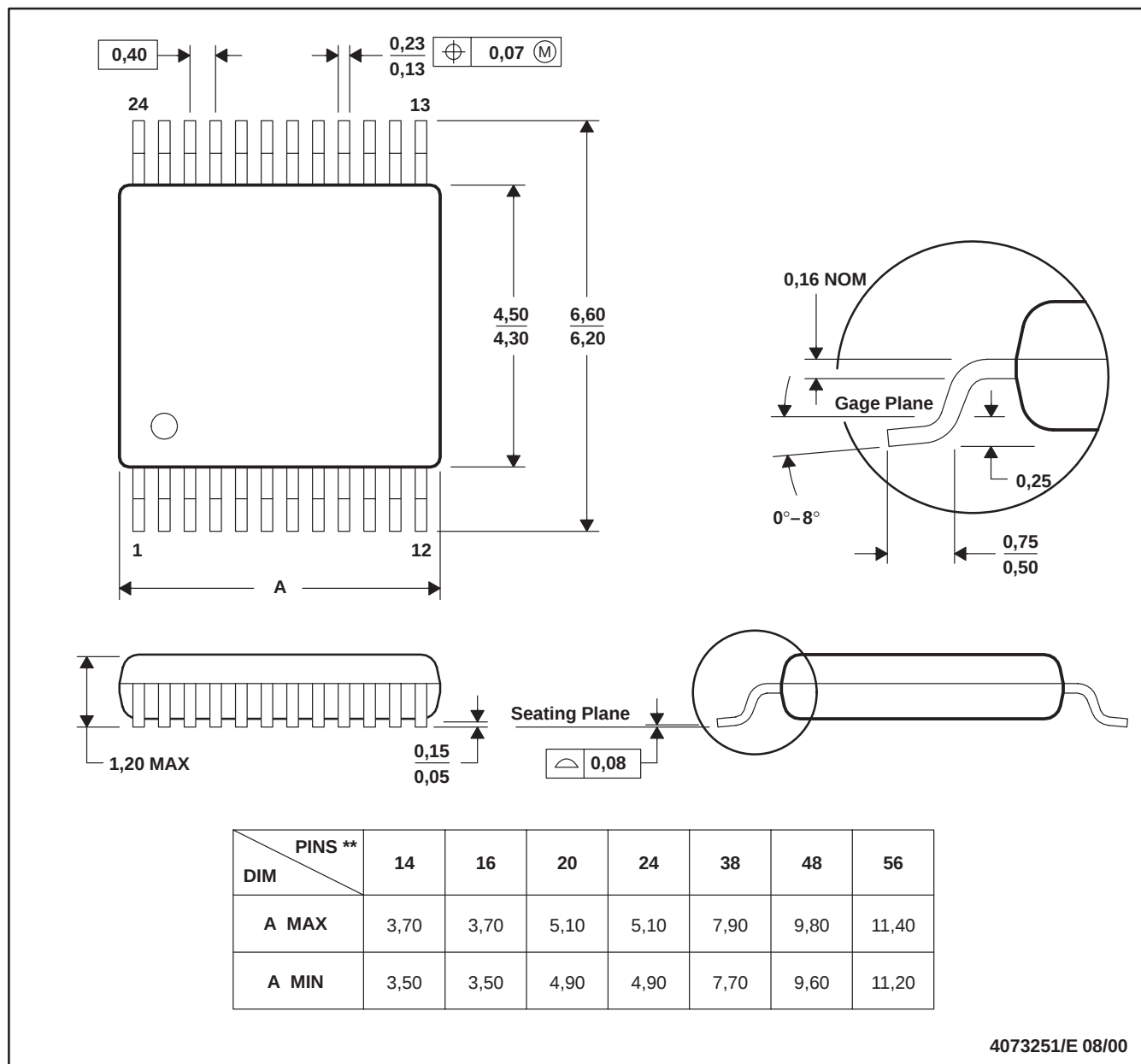
4040062/C 03/03

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

DGV (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

24 PINS SHOWN

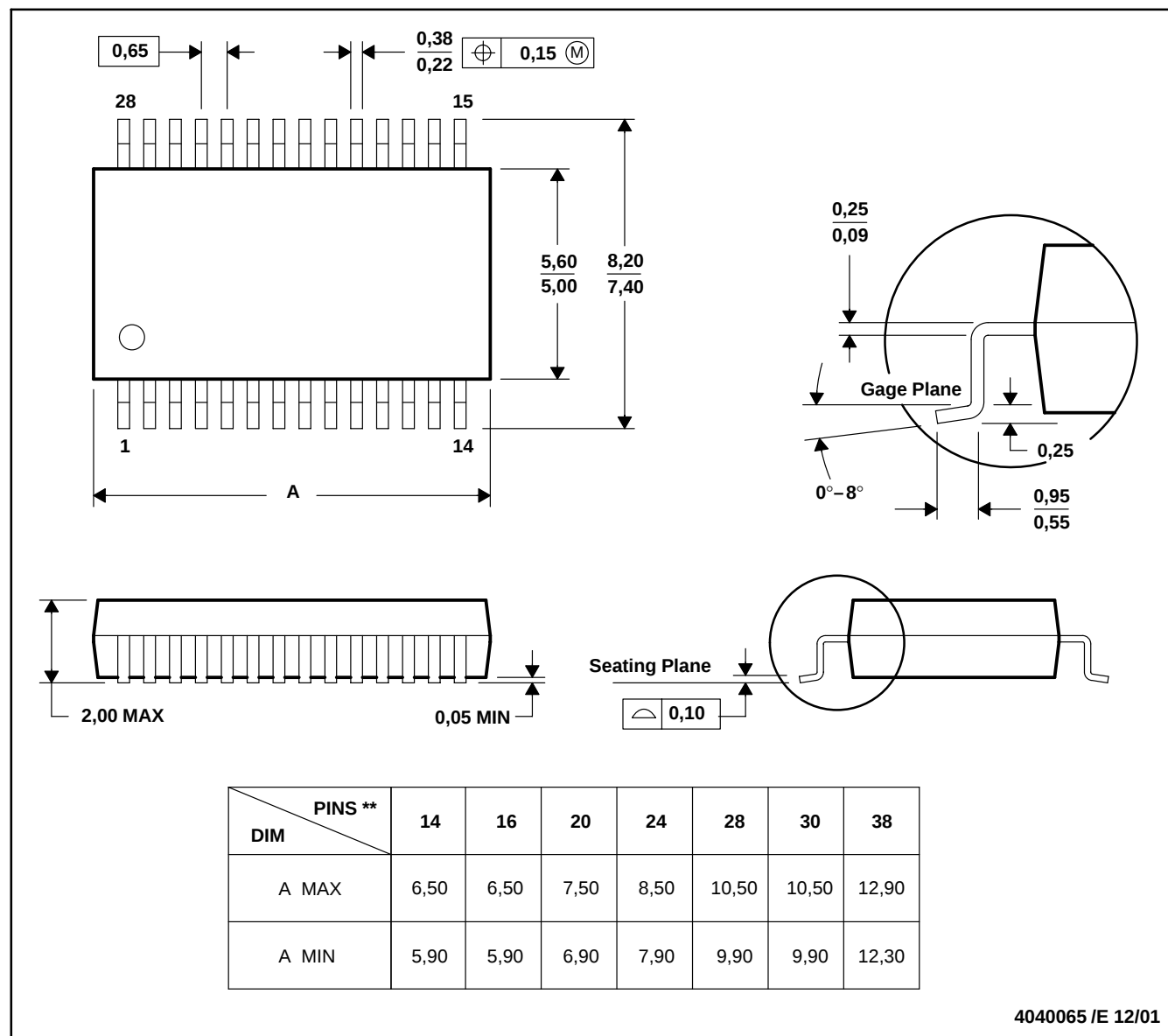


- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
 D. Falls within JEDEC: 24/48 Pins – MO-153
 14/16/20/56 Pins – MO-194

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 - Falls within JEDEC MO-150

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